L Number	Hits	Search Text	DB	Time stamp
-	90	nikoonahad-m\$.in.	USPAT; US-PGPUB; EPO; JPO;	2004/06/02 13:55
-	79	nikoonahad-m\$.in. and (semiconductor or wafer)	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/06/01 15:36
-	63	nikoonahad-mehrdad\$.in.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/06/01 15:36
_	57	nikoonahad-mehrdad\$.in. and (semiconductor or wafer)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/06/01 15:38
_	38	nikoonahad-mehrdad\$.in. and scatter\$.clm.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/06/01 15:40
-	22	nikoonahad-mehrdad\$.in. and (scatter\$ and rotat\$).clm.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/01 15:41
-	486	scatter\$.ab. and ((semiconductor or wafer) near4 surface) and scatter\$.clm.	USPĀT	2004/06/02 18:01
-	253	356/\$.ccls. and scatter\$.ab. and ((semiconductor or wafer) near4 surface) and scatter\$.clm.	USPAT	2004/06/02
_	46	356/\$.ccls. and scatter\$.ab. and ((semiconductor or wafer) near4 surface) and scatter\$.clm. and rotat\$.clm.	USPAT	2004/06/04 12:05
_	46	356/\$.ccls. and scatter\$.ab. and ((semiconductor or wafer) near4 surface) and rotat\$ and scatter\$.clm. and rotat\$.clm.	USPAT	2004/06/02 14:14
_	115	(356/\$ or 250/\$).ccls. and scatter\$.ab. and x\$1ray and (semiconductor or wafer)	USPAT	2004/06/02 14:16
-	31	(356/\$ or 250/\$).ccls. and scatter\$.ab. and x\$1ray and (semiconductor or wafer) and x\$1ray.clm.	USPAT	2004/06/02 17:12
-	35	(356/\$ or 250/\$).ccls. and scatter\$.ab. and (x\$1ray near6 source) and (semiconductor or wafer)	USPAT	2004/06/02 17:56
-	11	("4999014" "5042951" "5181080" "5329357" "5412473" "5596411" "5608526" "5771094"	USPAT	2004/06/03 16:13
-	4	"5747813" "5917594" "6323946").pn. ("6429943" "6433878" "6483580" "6451621").pn.	USPAT	2004/06/02 18:00
-	4	scatter\$.ab. and ((semiconductor or wafer) near4 surface) and (neural adj network)	USPAT	2004/06/04 15:55
-	2	("6399944" "6316151").pn.	USPAT	2004/06/04 15:33
-	10	("4999014" "5042951" "5181080" "5329357" "5412473" "5596411" "5608526" "5771094" "5747813" "5917594" "6323946" "6429943" "6433878" "6483580" "6451621").pn. and rotat\$	USPAT	2004/06/03

	7.7	[ ("4039370"   "4141780"   "4200396"	LICONO	0004/06/02
-	24	,	USPAT	2004/06/03
		"4303341"   "4330213"   "4408884"		16:14
İ		"4710642"   "4905170"   "5164790"		
i		"5241369"   "5329357"   "5381233"		
		"5416594"   "5607800"   "5608526"		l i
		"5739909"   "5757671"   "5835221"	İ	
		"5867276"   "5923423"   "5956148"		
		"5963329"   "6031615"   "6118525").PN.		
	15		IICDAM	2004/06/03
-	15		USPAT	2004/06/03
		"4303341"   "4330213"   "4408884"		16:15
		"4710642"   "4905170"   "5164790"		
		"5241369"   "5329357"   "5381233"		
	ļ	"5416594"   "5607800"   "5608526"		1
1		"5739909"   "5757671"   "5835221"		
ĺ	İ	"5867276"   "5923423"   "5956148"		
i		"5963329"   "6031615"   "6118525").PN.		
		and rotat\$		
<u> </u>	12		IICDAM	2004/06/03
-	12	, , , , , , , , , , , , , , , , , , , ,	USPAT	2004/06/03
		"4303341"   "4330213"   "4408884"		16:15
		"4710642"   "4905170"   "5164790"		
		"5241369"   "5329357"   "5381233"		1
		"5416594"   "5607800"   "5608526"		
		"5739909"   "5757671"   "5835221"		
		"5867276"   "5923423"   "5956148"	1	
		"5963329"   "6031615"   "6118525").PN.		
	1	and scatter\$ and rotat\$		
	1		11CDAM	2004/06/03
-	4		USPAT	2004/06/03
j	_	"5703692").PN.		16:26
-	3		USPAT	2004/06/03
		"5703692").PN. and scatter\$ and rotat\$		16:26
_	80	356/372.ior.	USPAT	2004/06/04
				11:30
_	4	356/372.ior. and scatter\$.ab.	USPAT	2004/06/04
		Jooy Jyz. 101: and Scattery. ab.	OSIAI	11:30
	1514	256/6 gay and gasttant ab	HCDAM	i l
-	1514	356/\$.cor. and scatter\$.ab.	USPAT	2004/06/04
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-	1299	356/\$.cor. and scatter\$.ab. and	USPAT	2004/06/04
		scatter\$.clm.	ļ	11:31
-	478	356/\$.cor. and scatter\$.ab. and	USPAT	2004/06/04
		scatter\$.clm. and @pd>19980101		11:32
_	208	356/\$.cor. and scatter\$.ab. and	USPAT	2004/06/04
		scatter\$.clm. and @pd>19980101 and		11:38
		(semiconductor or wafer)		11.50
	1 12		******	1 2224 /26 /24
1-	13	356/340.ccls. and scatter\$.clm. and	USPAT;	2004/06/04
		(semiconductor or wafer)	EPO; JPO;	11:47
			DERWENT;	
			IBM TDB	
-	50	356/301.ccls. and scatter\$.clm. and	USPAT;	2004/06/04
	1	(semiconductor or wafer)	EPO; JPO;	11:48
	]		DERWENT;	
	]		IBM TDB	
1_	1	("5164790").pn.		2004/06/04
1	1	( 3104/30 ).pm.	USPAT	2004/06/04
1		256/227 1 227 2 227 5		11:50
1 -	49		USPAT	2004/06/04
1	1	((semiconductor or wafer) near4 surface)		12:06
1		and scatter\$.clm. and rotat\$.clm.		
-	49		USPAT;	2004/06/04
		((semiconductor or wafer) near4 surface)	EPO; JPO;	16:17
		and scatter\$.clm. and rotat\$.clm.	DERWENT;	
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1_	9	356/335-343 ggla and //aa	IBM_TDB	2004/06/04
1 -		356/335-343.ccls. and ((semiconductor or	USPAT;	2004/06/04
		wafer) near4 surface) and scatter\$.clm.	EPO; JPO;	13:31
		and rotat\$.clm.	DERWENT;	
			IBM_TDB	
-	1	356/239.1-239.8.ccls. and ((semiconductor	USPAT;	2004/06/04
		or wafer) near4 surface) and	EPO; JPO;	14:57
		scatter\$.clm. and rotat\$.clm.	DERWENT;	· - ·
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